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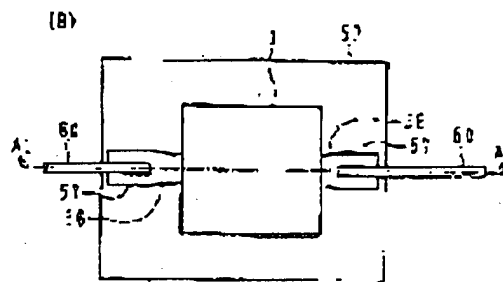
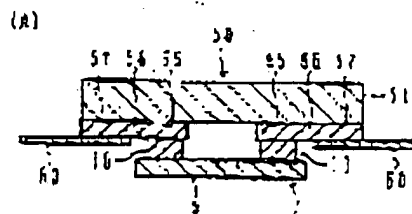
(54) SUPERCONDUCTIVE CIRCUIT DEVICE AND ITS MANUFACTURING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a superconductive circuit device in which a superconductive circuit board can be mounted on a mounting substrate, without using a normal conductive wire.

SOLUTION: A plurality of pads are disposed discretely on a main surface of a dielectric substrate. The pad is formed of an oxide superconductive material. A ground conductive film is arranged on a main surface of a dielectric substrate. The ground conductive film is formed of an oxide superconductive material. A dielectric film covers the surface of the ground conductive film. A superconductive circuit pattern is arranged on a surface of a dielectric film. A superconductive circuit pattern is connected to a pad. The sum of the thickness of a ground conductive film, a dielectric film and a superconductive circuit pattern is smaller than the height of a pad.

図1の要部を示す断面図



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